

**DIN EN 16603-20-06**

ICS 49.140

**Entwurf**

Einsprüche bis 2019-07-10  
Vorgesehen als Ersatz für  
DIN EN 16603-20-06:2014-09

**Raumfahrttechnik –  
Teil 20-06: Aufladung von Raumfahrzeugen;  
Englische Fassung prEN 16603-20-06:2019**

Space engineering –  
Part 20-06: Spacecraft charging;  
English version prEN 16603-20-06:2019

Ingénierie spatiale –  
Partie 20-06: Charges électrostatique des véhicules spatiales;  
Version anglaise prEN 16603-20-06:2019

**Anwendungswarnvermerk**

Dieser Norm-Entwurf mit Erscheinungsdatum 2019-05-10 wird der Öffentlichkeit zur Prüfung und Stellungnahme vorgelegt.

Weil die beabsichtigte Norm von der vorliegenden Fassung abweichen kann, ist die Anwendung dieses Entwurfs besonders zu vereinbaren.

Stellungnahmen werden erbeten

- vorzugsweise online im Norm-Entwurfs-Portal von DIN unter [www.din.de/go/entwuerfe](http://www.din.de/go/entwuerfe) bzw. für Norm-Entwürfe der DKE auch im Norm-Entwurfs-Portal der DKE unter [www.entwuerfe.normenbibliothek.de](http://www.entwuerfe.normenbibliothek.de), sofern dort wiedergegeben;
- oder als Datei per E-Mail an [nl@din.de](mailto:nl@din.de) möglichst in Form einer Tabelle. Die Vorlage dieser Tabelle kann im Internet unter [www.din.de/go/stellungnahmen-norm-entwuerfe](http://www.din.de/go/stellungnahmen-norm-entwuerfe) oder für Stellungnahmen zu Norm-Entwürfen der DKE unter [www.dke.de/stellungnahme](http://www.dke.de/stellungnahme) abgerufen werden;
- oder in Papierform an den DIN-Normenausschuss Luft- und Raumfahrt (NL), 10772 Berlin, Saatwinkler Damm 42/43, 13627 Berlin.

Die Empfänger dieses Norm-Entwurfs werden gebeten, mit ihren Kommentaren jegliche relevanten Patentrechte, die sie kennen, mitzuteilen und unterstützende Dokumentationen zur Verfügung zu stellen.

Gesamtumfang 132 Seiten

DIN-Normenausschuss Luft- und Raumfahrt (NL)

## Nationales Vorwort

Dieses Dokument (prEN 16603-20-06:2019) wurde vom Technischen Komitee CEN/CLC/JTC 5 „Raumfahrt“ erarbeitet, dessen Sekretariat von DIN (Deutschland) gehalten wird.

Das zuständige deutsche Normungsgremium ist der Arbeitsausschuss NA 131-06-02 AA „Interoperabilität von Informations-, Kommunikations- und Navigationssystemen“ im DIN-Normungsausschuss Luft- und Raumfahrt (NL).

Dieses Dokument wird EN 16603-20-06:2014 ersetzen.

Dieses Dokument enthält unter Berücksichtigung des DIN-Präsidialbeschlusses 1/2004 nur die englische Originalfassung von prEN 16603-20-06:2019.

## Änderungen

Gegenüber DIN EN 16603-20-06:2014-09 wurden folgende Änderungen vorgenommen:

- a) zu Abschnitt 3.2 den Begriff „Überschlagstrom“ hinzugefügt;
- b) zu Abschnitt 3.3 die Abkürzungen „RIC“ und „SPIS“ hinzugefügt;
- c) Abschnitt 3.4 „Nomenklatur“ hinzugefügt;
- d) in Abschnitten 4.1.1, 4.1.2, 6.1.3, 6.2.1, 6.3.1, 6.3.2, 6.3.3.2, 6.3.3.4, 6.3.3.6, 6.4, 6.6.1, 6.6.2, 6.6.3, 6.7, 6.8.1, 6.8.2, 6.8.4, 7.1, 7.2.2, 7.2.3.1, 7.2.3.2, 7.3, 9.2.2, 9.2.3, 9.3, 11.2.1, 11.2.2, 11.3.5, B.2.1, B.2.2, B.4, B.7, C.3.9, C.4, C.5.4.3, C.5.5, C.9.4.2, C.9.6.3, D.1.1.6, D.2.4, D.3.1, E.1, E.2.5.2, E.2.5.3, E.3.4 Angaben geändert und/oder hinzugefügt;
- e) Norm redaktionell überarbeitet.

## Nationaler Anhang NA (informativ)

### Begriffe

### 3 Begriffe und Abkürzungen

#### 3.1 In anderen Normen definierte Begriffe

Für die Anwendung dieser Norm gelten die Begriffe nach ECSS-S-ST-00-01.

#### 3.2 Für diese Norm spezifische Begriffe

##### 3.2.1

##### **Aluminium-Äquivalentdicke**

Dicke von Aluminium mit einer Massendichte je Flächeneinheit, die der des beschriebenen Werkstoffs entspricht

ANMERKUNG Die Massendichte wird gewöhnlich in ( $\text{g cm}^{-2}$ ) gemessen.

##### 3.2.2

##### **Polarlichtzone**

Gebiet zwischen dem 60. und 70. Grad nördlicher oder südlicher Breite, in dem Polarlichter auftreten

##### 3.2.3

##### **dielektrische Tiefenaufladung**

elektrische Aufladung innerhalb der Masse eines außen oder innen liegenden Werkstoffs

##### 3.2.4

##### **Dielektrikum**

ein Medium, in dem ein elektrisches Feld aufrechterhalten werden kann

ANMERKUNG In Abhängigkeit von ihrem spezifischen Widerstand können dielektrische Werkstoffe als isolierend, antistatisch, schwach leitfähig oder leitfähig beschrieben werden. Folgendes ist ein klassisches Beispiel der Klassifikation nach spezifischem Widerstand:

- über  $10^9 \Omega\text{m}$ : isolierend;
- zwischen  $10^2 \Omega\text{m}$  und  $10^9 \Omega\text{m}$ : antistatisch;
- zwischen  $10^3 \Omega\text{m}$  und  $10^6 \Omega\text{m}$ : statisch ableitend;
- zwischen  $10^{-2} \Omega\text{m}$  und  $10^2 \Omega\text{m}$ : schwach leitfähig;
- unterhalb  $10^{-2} \Omega\text{m}$ : leitfähig.

##### 3.2.5

##### **Dosis**

örtlich aufgenommene Energie je Masseneinheit aufgrund von **Strahlungswirkung**

##### 3.2.6

##### **Abströmseite**

<bezogen auf einen Gegenstand in relativer Bewegung gegenüber einem **Plasma**> die Seite eines Gegenstands in Richtung des **Plasmageschwindigkeitsvektors**

### 3.2.7

#### **elektrostatisch**

bezogen auf statische Elektrizität oder Elektrizität im Ruhezustand

### 3.2.8

#### **elektrostatischer Funke**

Versagen der isolierenden Eigenschaften eines **Dielektrikums**, das zu einer plötzlichen Entladung und einem Risiko der Beschädigung des betreffenden **Dielektrikums** führt

### 3.2.9

#### **elektrostatische Entladung**

schnelle, spontane Übertragung elektrischer Ladung, induziert durch ein starkes **elektrostatisches** Feld

### 3.2.10

#### **äußere Aufladung**

elektrische Aufladung von außen liegenden Werkstoffen

### 3.2.11

#### **Überschlagstrom**

Strom, der sich durch eine sich an der Oberfläche ausbreitende Entladung ausbildet

### 3.2.12

#### **Fluenz**

zeitliches Integral der Flussdichte

### 3.2.13

#### **Isolator**

isolierendes Dielektrikum

### 3.2.14

#### **innere Aufladung**

elektrische Aufladung von innen liegenden Werkstoffen, die zumindest von der Hülle des Raumfahrzeugs abgeschirmt sind, aufgrund des Eindringens geladener Teilchen aus dem umgebenden Medium

ANMERKUNG Werkstoffe können Leiter oder Dielektrika sein.

### 3.2.15

#### **innere dielektrische Aufladung**

innere Aufladung **dielektrischer** Werkstoffe

### 3.2.16

#### **Ionentriebwerk**

Antriebssystem, das durch den Ausstoß von Ionen mit hohen Geschwindigkeiten arbeitet

### 3.2.17

#### **L-Schale**

Parameter des Erdmagnetfelds

ANMERKUNG 1 Sie wird auch mit L bezeichnet und als Koordinate zur Lagebeschreibung im erdnahen Weltraum verwendet.

ANMERKUNG 2 Die Ableitung von L oder L-Schale ist kompliziert und beruht auf einer Invarianz der Bewegung geladener Teilchen im Erdmagnetfeld. Allerdings unterstützt dies die Definition von Plasmaregimen innerhalb der Magnetosphäre, da es bei einem Dipolmagnetfeld gleich der geozentrischen Höhenlage in Erdradien der örtlichen Magnetfeldlinie bei Querung des Äquators ist.

### 3.2.18

#### **ungerichtete Flussdichte**

skalares Integral der Flussdichte über alle Richtungen

ANMERKUNG Dies besagt, dass die Richtungsverteilung, die auch nicht-isotrop sein kann, nicht berücksichtigt wird. Die Flussdichte an einem Punkt ist die Anzahl der Teilchen, die eine Kugel mit Querschnittsflächeneinheit (d. h. Radius) durchdringen. Eine ungerichtete Flussdichte darf nicht mit einer isotropen Flussdichte verwechselt werden.

### 3.2.19

#### **Ausgasrate**

Masse einer Molekülspezies, die von einem Material je Zeiteinheit und je Flächeneinheit ausgeht

ANMERKUNG Die Einheit der Ausgasrate ist  $\text{g cm}^{-2} \text{s}^{-1}$ . Sie kann auch in anderen Einheiten angegeben werden, wie z. B. in relativer Masseneinheit je Zeiteinheit ( $\text{g s}^{-1}$ ), ( $\% \text{s}^{-1}$ ) oder ( $\% \text{s}^{-1} \text{cm}^{-2}$ ).

### 3.2.20

#### **Plasma**

teilweise oder vollständig ionisiertes Gas, dessen Teilchen ein gemeinsames Verhalten in dessen elektromagnetischem Feld aufweisen

### 3.2.21

#### **Primärentladung**

erste elektrostatische Entladung, die durch Erzeugung einer vorübergehenden Leiterbahn zu einem Sekundärbogen führen kann

### 3.2.22

#### **Strahlung**

Energieübertragung durch Teilchen (einschließlich Photonen)

ANMERKUNG Im Sinne dieser Norm wird elektromagnetische Strahlung unterhalb des UV-Bereiches nicht behandelt. Somit werden sichtbare, Wärme-, Mikrowellen- und Radiowellenstrahlung nicht behandelt.

### 3.2.23

#### **Strahlungsgürtel**

Bereich gebundener oder quasigebundener energiereicher Teilchen im Erdmagnetfeld

### 3.2.24

#### **Staustrahl**

Volumen in unmittelbarer Umgebung und in Bewegungsrichtung des Raumfahrzeugs, in dem Veränderungen von Oberfläche oder **Plasma** aufgrund des Durchgangs eines Raumfahrzeugs durch das Medium auftreten können

### 3.2.25

#### **Sekundärbogen**

Durchgang eines Stroms von einer äußeren Quelle, wie einer Solaranlage, durch eine ursprünglich von einer **Primärentladung** erzeugten Leiterbahn

### 3.2.26

#### **Oberflächenaufladung**

elektrische Aufladung der Oberfläche von außen oder innen liegendem Werkstoff

### 3.2.27

#### **Verbindungsvorrichtung**

flexibles leitfähiges oder nicht leitendes Kabel, das zwei Raumfahrzeuge oder zwei Teile desselben Raumfahrzeugs ohne jede weitere mechanische Befestigung miteinander verbindet

### 3.2.28

#### Schubdüse

Einrichtung zur Änderung der Fluglage oder Umlaufbahn eines Raumfahrzeugs im Weltraum nach dem Reaktionsprinzip

ANMERKUNG Beispielsweise Rakete, Kaltgas-Emitter und elektrischer Antrieb.

### 3.2.29

#### Tripelpunkt

<bezogen auf den Beginn elektrostatischer Entladung> Punkt des Aufeinandertreffens von **Dielektrikum**, Metall und Vakuum

### 3.2.30

#### Zuströmseite

<bezogen auf einen Gegenstand in relativer Bewegung gegenüber einem **Plasma**> die Seite eines Gegenstands in entgegengesetzter Richtung des **Plasmageschwindigkeitsvektors**

### 3.2.31

#### Wirbelschleppe

Volumen in unmittelbarer Umgebung und entgegengesetzt der Bewegungsrichtung des Raumfahrzeugs, in dem Veränderungen des umgebenden **Plasmas** aufgrund des Durchgangs eines Raumfahrzeugs durch das Medium auftreten können

## 3.3 Abkürzungen

In dieser Norm werden die folgenden Abkürzungen definiert und verwendet.

| Abkürzung | Bedeutung |
|-----------|-----------|
|-----------|-----------|

|             |                                                                                          |
|-------------|------------------------------------------------------------------------------------------|
| <b>AOCS</b> | Lage- und Bahnregelungssystem (en: attitude and orbital control system)                  |
| <b>DGD</b>  | Entladung mit direktem Gradienten (en: direct gradient discharge)                        |
| <b>EMV</b>  | elektromagnetische Verträglichkeit (en: electromagnetic compatibility, EMC)              |
| <b>emf</b>  | elektromotorische Kraft (en: electro-motive force)                                       |
| <b>EP</b>   | elektrischer Antrieb (en: electric propulsion)                                           |
| <b>ESD</b>  | elektrostatische Entladung (en: electrostatic discharge)                                 |
| <b>ETFE</b> | Ethylen-Tetrafluorethylen-Copolymer (en: ethylene-tetrafluoroethylene copolymer)         |
| <b>eV</b>   | Elektronvolt (en: electron volt) (auch keV, MeV)                                         |
| <b>FEED</b> | Feldemissionselektroantrieb (en: field emission electric propulsion)                     |
| <b>FEP</b>  | Fluorethylenpropylen (en: fluoroethylene-propylene)                                      |
| <b>GEO</b>  | geostationäre Erdumlaufbahn (en: geostationary Earth orbit)                              |
| <b>HEO</b>  | hochexzentrische Umlaufbahn (en: highly eccentric orbit)                                 |
| <b>ISS</b>  | Internationale Raumstation (en: International Space Station)                             |
| <b>IVG</b>  | invertierter Spannungsgradient (en: inverted voltage gradient)                           |
| <b>IVGD</b> | Entladung mit invertiertem Spannungsgradienten (en: inverted voltage gradient discharge) |
| <b>LEO</b>  | erdnahe Umlaufbahn (en: low Earth orbit)                                                 |
| <b>MEMS</b> | mikroelektromechanische(s) System(e) [en: micro-electromechanical system(s)]             |
| <b>MEO</b>  | mittlere Erdumlaufbahn [en: medium (altitude) Earth orbit]                               |

**Abkürzung    Bedeutung**

|               |                                                                                                               |
|---------------|---------------------------------------------------------------------------------------------------------------|
| <b>MLI</b>    | Mehrschichtisolierung (en: multi-layer insulation)                                                            |
| <b>MLT</b>    | magnetische Ortszeit (en: magnetic local time)                                                                |
| <b>NASA</b>   | Nationale Luft- und Raumfahrtbehörde (en: National Aeronautics and Space Administration)                      |
| <b>NGD</b>    | Entladung mit normalem Gradienten (en: normal gradient discharge)                                             |
| <b>PCB</b>    | Leiterplatte (en: printed circuit board)                                                                      |
| <b>PEO</b>    | polare Erdumlaufbahn (en: polar Earth orbit)                                                                  |
| <b>PTFE</b>   | Polytetrafluorethylen (en: poly-tetrafluoroethylene)                                                          |
| <b>PVA</b>    | photovoltaische Baugruppe (en: photo-voltaic assembly)                                                        |
| <b>RIC</b>    | strahlungsinduzierte Leitfähigkeit (en: radiation induced conductivity)                                       |
| <b>r.m.s.</b> | Effektivwert (en: root-mean-square)                                                                           |
| <b>SAS</b>    | Solaranlagen Simulator (en: solar array simulator)                                                            |
| <b>SPIS</b>   | Simulation der Wechselwirkung zwischen Raumfahrzeug und Plasma (en: spacecraft plasma interaction simulation) |
| <b>SPT</b>    | Antrieb mit breitem Beschleunigungskanal (en: stationary plasma thruster)                                     |
| <b>SSM</b>    | rückseitig beschichteter Spiegel (en: second surface mirror)                                                  |
| <b>UV</b>     | ultraviolettes Licht (en: ultra-violet light)                                                                 |

### **3.4    Nomenklatur**

Für dieses Dokument gilt die folgende Nomenklatur:

- a) Das Wort „müssen“ (en: shall) wird in dieser Norm zur Formulierung von Anforderungen verwendet. Sämtliche Anforderungen werden durch das Wort „müssen“ ausgedrückt.
- b) Das Wort „sollten“ (en: should) wird in dieser Norm zur Formulierung von Empfehlungen verwendet. Sämtliche Empfehlungen werden durch das Wort „sollten“ ausgedrückt.

ANMERKUNG    Es ist zu erwarten, dass die Empfehlungen in diesem Dokument während der Anpassung entweder in Anforderungen umgewandelt oder gestrichen werden.

- c) Die Wörter „dürfen“ (en: may) und „brauchen nicht“ (en: need not) werden in dieser Norm zur Formulierung der Zulässigkeit oder Unzulässigkeit verwendet. Sämtliche Zulässigkeiten werden über das Wort „dürfen“ ausgedrückt. Sämtliche Unzulässigkeiten werden über die Wörter „brauchen nicht“ ausgedrückt.
- d) Das Wort „können“ (en: can) wird in dieser Norm zur Formulierung von Fähigkeiten oder Möglichkeiten verwendet und stellt daher, wenn nicht durch eines der vorstehenden Worte begleitet, einen beschreibenden Text dar.

ANMERKUNG    Beim ECSS haben „dürfen“ (en: may) und „können“ (en: can) völlig unterschiedliche Bedeutungen: „dürfen“ wird normativ (Zulässigkeit) und „können“ beschreibend verwendet.

- e) Zeitformen der Gegenwart und Vergangenheit werden in dieser Norm verwendet, um Tatsachenaussagen zu treffen, und stellen daher einen beschreibenden Text dar.

— Leerseite —

May 2019

ICS 49.140

Will supersede EN 16603-20-06:2014

English version

## Space engineering - Spacecraft charging

Ingénierie spatiale - Charges électrostatique des  
véhicules spatiales

Raumfahrttechnik - Aufladung von Raumfahrzeugen

This draft European Standard is submitted to CEN members for enquiry. It has been drawn up by the Technical Committee CEN/CLC/JTC 5.

If this draft becomes a European Standard, CEN and CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

This draft European Standard was established by CEN and CENELEC in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CEN and CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CEN and CENELEC members are the national standards bodies and national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and United Kingdom.

Recipients of this draft are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation. Recipients of this draft are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

**Warning :** This document is not a European Standard. It is distributed for review and comments. It is subject to change without notice and shall not be referred to as a European Standard.



CEN-CENELEC Management Centre:  
Rue de la Science 23, B-1040 Brussels

## Table of contents

|                                                                                          |           |
|------------------------------------------------------------------------------------------|-----------|
| <b>European Forewod .....</b>                                                            | <b>9</b>  |
| <b>Introduction.....</b>                                                                 | <b>10</b> |
| <b>1 Scope.....</b>                                                                      | <b>12</b> |
| <b>2 Normative references .....</b>                                                      | <b>13</b> |
| <b>3 Terms, definitions and abbreviated terms.....</b>                                   | <b>14</b> |
| 3.1 Terms defined in other standards .....                                               | 14        |
| 3.2 Terms specific to the present standard .....                                         | 14        |
| 3.3 Abbreviated terms.....                                                               | 17        |
| 3.4 Nomenclature .....                                                                   | 18        |
| <b>4 Overview.....</b>                                                                   | <b>20</b> |
| 4.1 Plasma interaction effects.....                                                      | 20        |
| 4.1.1 Presentation.....                                                                  | 20        |
| 4.1.2 Most common engineering concerns.....                                              | 20        |
| 4.1.3 Overview of physical mechanisms .....                                              | 21        |
| 4.2 Relationship with other standards .....                                              | 23        |
| <b>5 Protection programme .....</b>                                                      | <b>25</b> |
| <b>6 Surface material requirements .....</b>                                             | <b>26</b> |
| 6.1 Overview .....                                                                       | 26        |
| 6.1.1 Description and applicability.....                                                 | 26        |
| 6.1.2 Purpose common to all spacecraft .....                                             | 27        |
| 6.1.3 A special case: scientific spacecraft with plasma measurement<br>instruments ..... | 27        |
| 6.2 General requirements .....                                                           | 27        |
| 6.2.1 Maximum permitted voltage .....                                                    | 27        |
| 6.2.2 Maximum resistivity.....                                                           | 28        |
| 6.3 Electrical continuity, including surfaces and structural and mechanical parts .....  | 28        |
| 6.3.1 Grounding of surface metallic parts.....                                           | 28        |
| 6.3.2 Exceptions .....                                                                   | 29        |

|           |                                                                                      |           |
|-----------|--------------------------------------------------------------------------------------|-----------|
| 6.3.3     | Electrical continuity for surface materials .....                                    | 30        |
| 6.4       | Surface charging analysis .....                                                      | 34        |
| 6.5       | Deliberate potentials .....                                                          | 34        |
| 6.6       | Testing of materials and assemblies .....                                            | 34        |
| 6.6.1     | General .....                                                                        | 34        |
| 6.6.2     | Material characterization tests .....                                                | 36        |
| 6.6.3     | Material and assembly qualification .....                                            | 36        |
| 6.7       | Scientific spacecraft with plasma measurement instruments .....                      | 37        |
| 6.8       | Verification .....                                                                   | 37        |
| 6.8.1     | Grounding .....                                                                      | 37        |
| 6.8.2     | Material selection .....                                                             | 38        |
| 6.8.3     | Environmental effects .....                                                          | 38        |
| 6.8.4     | Computer modelling .....                                                             | 38        |
| 6.9       | Triggering of ESD .....                                                              | 39        |
| <b>7</b>  | <b>Secondary arc requirements .....</b>                                              | <b>40</b> |
| 7.1       | Description and applicability .....                                                  | 40        |
| 7.2       | Solar arrays .....                                                                   | 41        |
| 7.2.1     | Overview .....                                                                       | 41        |
| 7.2.2     | General requirement .....                                                            | 41        |
| 7.2.3     | Testing of solar arrays .....                                                        | 41        |
| 7.3       | Other exposed parts of the power system including solar array drive mechanisms ..... | 46        |
| <b>8</b>  | <b>High voltage system requirements .....</b>                                        | <b>47</b> |
| 8.1       | Description .....                                                                    | 47        |
| 8.2       | Requirements .....                                                                   | 47        |
| 8.3       | Validation .....                                                                     | 47        |
| <b>9</b>  | <b>Internal parts and materials requirements .....</b>                               | <b>48</b> |
| 9.1       | Description .....                                                                    | 48        |
| 9.2       | General .....                                                                        | 48        |
| 9.2.1     | Internal charging and discharge effects .....                                        | 48        |
| 9.2.2     | Grounding and connectivity .....                                                     | 48        |
| 9.2.3     | Dielectric electric fields and voltages .....                                        | 49        |
| 9.3       | Validation .....                                                                     | 50        |
| <b>10</b> | <b>Tether requirements .....</b>                                                     | <b>54</b> |
| 10.1      | Description .....                                                                    | 54        |
| 10.2      | General .....                                                                        | 54        |

|                |                                                                                              |           |
|----------------|----------------------------------------------------------------------------------------------|-----------|
| 10.2.1         | Hazards arising on tethered spacecraft due to voltages generated by conductive tethers ..... | 54        |
| 10.2.2         | Current collection and resulting problems .....                                              | 54        |
| 10.2.3         | Hazards arising from high currents flowing through the tether and spacecraft structures..... | 55        |
| 10.2.4         | Continuity of insulation.....                                                                | 55        |
| 10.2.5         | Hazards from undesired conductive paths .....                                                | 55        |
| 10.2.6         | Hazards from electro-dynamic tether oscillations .....                                       | 55        |
| 10.2.7         | Other effects .....                                                                          | 55        |
| 10.3           | Validation.....                                                                              | 56        |
| <b>11</b>      | <b>Electric propulsion requirements .....</b>                                                | <b>57</b> |
| 11.1           | Overview .....                                                                               | 57        |
| 11.1.1         | Description.....                                                                             | 57        |
| 11.1.2         | Coverage of the requirements.....                                                            | 57        |
| 11.2           | General.....                                                                                 | 59        |
| 11.2.1         | Spacecraft neutralization.....                                                               | 59        |
| 11.2.2         | Beam neutralization .....                                                                    | 60        |
| 11.2.3         | Contamination.....                                                                           | 60        |
| 11.2.4         | Sputtering .....                                                                             | 61        |
| 11.2.5         | Neutral gas effects .....                                                                    | 61        |
| 11.3           | Validation.....                                                                              | 61        |
| 11.3.1         | Ground testing .....                                                                         | 61        |
| 11.3.2         | Computer modelling characteristics .....                                                     | 62        |
| 11.3.3         | In-flight monitoring.....                                                                    | 62        |
| 11.3.4         | Sputtering .....                                                                             | 62        |
| 11.3.5         | Neutral gas effects .....                                                                    | 62        |
| <b>Annex A</b> | <b>(normative) Electrical hazard mitigation plan - DRD .....</b>                             | <b>64</b> |
| A.1            | DRD identification.....                                                                      | 64        |
| A.1.1          | Requirement identification and source document.....                                          | 64        |
| A.1.2          | Purpose and objective.....                                                                   | 64        |
| A.2            | Expected response .....                                                                      | 64        |
| A.2.1          | Scope and content .....                                                                      | 64        |
| A.2.2          | Special remarks .....                                                                        | 65        |
| <b>Annex B</b> | <b>(informative) Tailoring guidelines.....</b>                                               | <b>66</b> |
| B.1            | Overview .....                                                                               | 66        |
| B.2            | LEO .....                                                                                    | 66        |
| B.2.1          | General .....                                                                                | 66        |

|                                                                            |                                                       |           |
|----------------------------------------------------------------------------|-------------------------------------------------------|-----------|
| B.2.2                                                                      | LEO orbits with high inclination .....                | 67        |
| B.3                                                                        | MEO and GEO orbits.....                               | 67        |
| B.4                                                                        | Spacecraft with onboard plasma detectors .....        | 67        |
| B.5                                                                        | Tethered spacecraft.....                              | 68        |
| B.6                                                                        | Active spacecraft .....                               | 68        |
| B.7                                                                        | Solar Wind .....                                      | 68        |
| B.8                                                                        | Other planetary magnetospheres.....                   | 68        |
| <b>Annex C (informative) Physical background to the requirements .....</b> |                                                       | <b>69</b> |
| C.1                                                                        | Introduction.....                                     | 69        |
| C.2                                                                        | Definition of symbols.....                            | 69        |
| C.3                                                                        | Electrostatic sheaths.....                            | 69        |
| C.3.1                                                                      | Introduction .....                                    | 69        |
| C.3.2                                                                      | The electrostatic potential .....                     | 70        |
| C.3.3                                                                      | The Debye length.....                                 | 70        |
| C.3.4                                                                      | Presheath .....                                       | 71        |
| C.3.5                                                                      | Models of current through the sheath.....             | 72        |
| C.3.6                                                                      | Thin sheath – space-charge-limited model.....         | 72        |
| C.3.7                                                                      | Thick sheath – orbit motion limited (OML) model ..... | 73        |
| C.3.8                                                                      | General case.....                                     | 74        |
| C.3.9                                                                      | Magnetic field modification of charging currents..... | 74        |
| C.4                                                                        | Current collection and grounding to the plasma .....  | 74        |
| C.5                                                                        | External surface charging .....                       | 75        |
| C.5.1                                                                      | Definition.....                                       | 75        |
| C.5.2                                                                      | Processes .....                                       | 75        |
| C.5.3                                                                      | Effects.....                                          | 76        |
| C.5.4                                                                      | Surface emission processes .....                      | 76        |
| C.5.5                                                                      | Floating potential.....                               | 77        |
| C.5.6                                                                      | Conductivity and resistivity .....                    | 78        |
| C.5.7                                                                      | Time scales.....                                      | 80        |
| C.6                                                                        | Spacecraft motion effects .....                       | 80        |
| C.6.1                                                                      | Wakes.....                                            | 80        |
| C.6.2                                                                      | Motion across the magnetic field .....                | 83        |
| C.7                                                                        | Induced plasmas .....                                 | 84        |
| C.7.1                                                                      | Definition.....                                       | 84        |
| C.7.2                                                                      | Electric propulsion thrusters .....                   | 85        |
| C.7.3                                                                      | Induced plasma characteristics .....                  | 85        |
| C.7.4                                                                      | Charge-exchange effects .....                         | 86        |

|                              |                                                      |            |
|------------------------------|------------------------------------------------------|------------|
| C.7.5                        | Neutral particle effects .....                       | 87         |
| C.7.6                        | Effect on floating potential.....                    | 87         |
| C.8                          | Internal and deep-dielectric charging .....          | 87         |
| C.8.1                        | Definition.....                                      | 87         |
| C.8.2                        | Relationship to surface charging .....               | 88         |
| C.8.3                        | Charge deposition .....                              | 89         |
| C.8.4                        | Material conductivity.....                           | 89         |
| C.8.5                        | Time dependence .....                                | 92         |
| C.8.6                        | Geometric considerations.....                        | 92         |
| C.8.7                        | Isolated internal conductors .....                   | 93         |
| C.8.8                        | Electric field sensitive systems .....               | 93         |
| C.9                          | Discharges and transients .....                      | 94         |
| C.9.1                        | General definition.....                              | 94         |
| C.9.2                        | Review of the process.....                           | 94         |
| C.9.3                        | Dielectric material discharge. ....                  | 95         |
| C.9.4                        | Metallic discharge .....                             | 97         |
| C.9.5                        | Internal dielectric discharge.....                   | 98         |
| C.9.6                        | Secondary powered discharge.....                     | 99         |
| C.9.7                        | Discharge thresholds .....                           | 99         |
| <b>Annex D (informative)</b> | <b>Charging simulation.....</b>                      | <b>101</b> |
| D.1                          | Surface charging codes .....                         | 101        |
| D.1.1                        | Introduction .....                                   | 101        |
| D.2                          | Internal charging codes .....                        | 103        |
| D.2.1                        | DICTAT.....                                          | 103        |
| D.2.2                        | ESADDC.....                                          | 103        |
| D.2.3                        | GEANT-4 .....                                        | 104        |
| D.2.4                        | NOVICE .....                                         | 104        |
| D.3                          | Environment model for internal charging.....         | 104        |
| D.3.1                        | FLUMIC .....                                         | 104        |
| D.3.2                        | Worst case GEO spectrum.....                         | 104        |
| <b>Annex E (informative)</b> | <b>Testing and measurement. ....</b>                 | <b>105</b> |
| E.1                          | Definition of symbols.....                           | 105        |
| E.2                          | Solar array testing.....                             | 105        |
| E.2.1                        | Solar cell sample.....                               | 105        |
| E.2.2                        | Pre-testing of the solar array simulator (SAS) ..... | 106        |
| E.2.3                        | Solar array test procedure.....                      | 108        |
| E.2.4                        | Other elements .....                                 | 112        |

|                                                                                                                                                                            |                                                                                                         |            |           |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------|------------|-----------|
| E.2.5                                                                                                                                                                      | The solar panel simulation device .....                                                                 | 113        |           |
| E.3                                                                                                                                                                        | Measurement of conductivity and resistivity .....                                                       | 115        |           |
| E.3.1                                                                                                                                                                      | Determination of intrinsic bulk conductivity by direct measurement .....                                | 115        |           |
| E.3.2                                                                                                                                                                      | Determination of radiation-induced conductivity coefficients by direct measurement .....                | 116        |           |
| E.3.3                                                                                                                                                                      | Determination of conductivity and radiation-induced conductivity by electron irradiation.....           | 117        |           |
| E.3.4                                                                                                                                                                      | The ASTM method for measurement of surface resistivity and its adaptation for space used materials..... | 117        |           |
| <b>References .....</b>                                                                                                                                                    |                                                                                                         | <b>120</b> |           |
| <b>Bibliography.....</b>                                                                                                                                                   |                                                                                                         | <b>124</b> |           |
| <br><b>Figures</b>                                                                                                                                                         |                                                                                                         |            |           |
| Figure 6-1: Applicability of electrical continuity requirements .....                                                                                                      |                                                                                                         | 31         |           |
| Figure 7-1: Solar array test set-up .....                                                                                                                                  |                                                                                                         | 44         |           |
| <br><b>Figure C-1 : Schematic diagram of potential variation through sheath and pre-sheath.....</b>                                                                        |                                                                                                         |            | <b>71</b> |
| <b>Figure C-2 : Example secondary yield curve .....</b>                                                                                                                    |                                                                                                         | <b>77</b>  |           |
| <b>Figure C-3 : Schematic diagram of wake structure around an object at relative motion with respect to a plasma .....</b>                                                 |                                                                                                         | <b>81</b>  |           |
| <b>Figure C-4 : Schematic diagram of void region .....</b>                                                                                                                 |                                                                                                         | <b>82</b>  |           |
| <b>Figure C-5 : Schematic diagram of internal charging in a planar dielectric .....</b>                                                                                    |                                                                                                         | <b>88</b>  |           |
| <b>Figure C-6 : Dielectric discharge mechanism.....</b>                                                                                                                    |                                                                                                         | <b>96</b>  |           |
| <b>Figure C-7 :Shape of the current in relation to discharge starting point.....</b>                                                                                       |                                                                                                         | <b>96</b>  |           |
| <b>Figure C-8 : Example of discharge on pierced aluminized Teflon® irradiated by electrons with energies ranging from 0 to 220 keV. ....</b>                               |                                                                                                         | <b>97</b>  |           |
| <b>Figure C-9 : Schematic diagram of discharge at a triple point in the inverted voltage gradient configuration with potential contours indicated by colour scale.....</b> |                                                                                                         | <b>98</b>  |           |
| <b>Figure E-1 : Photograph of solar cells sample – Front face &amp; Rear face (Stentor Sample. Picture from Denis Payan - CNES®).....</b>                                  |                                                                                                         | <b>106</b> |           |
| <b>Figure E-2 : Schematic diagram of power supply test circuit.....</b>                                                                                                    |                                                                                                         | <b>107</b> |           |
| <b>Figure E-3 : Example of a measured power source switch response.....</b>                                                                                                |                                                                                                         | <b>107</b> |           |

|                                                                                                                      |     |
|----------------------------------------------------------------------------------------------------------------------|-----|
| Figure E-4 : Example solar array simulator.....                                                                      | 108 |
| Figure E-5 : Absolute capacitance of the satellite .....                                                             | 109 |
| Figure E-6 : Junction capacitance of a cell versus to voltage .....                                                  | 111 |
| Figure E-7 : The shortened solar array sample and the missing capacitances .....                                     | 112 |
| Figure E-8 : Discharging circuit oscillations .....                                                                  | 113 |
| Figure E-9 : Effect of an added resistance in the discharging circuit (SAS + resistance) .....                       | 113 |
| Figure E-10 : Setup simulating the satellite including flashover current .....                                       | 114 |
| Figure E-11 : Basic arrangement of apparatus for measuring dielectric conductivity in planar samples .....           | 115 |
| Figure E-12 : Arrangement for measuring cable dielectric conductivity and cross-section through co-axial cable ..... | 115 |
| Figure E-13 : Arrangement for carrying out conductivity tests on planar samples under irradiation.....               | 117 |
| Figure E-14 : Basic experimental set up for surface conductivity .....                                               | 119 |

## Tables

|                                                                                                        |    |
|--------------------------------------------------------------------------------------------------------|----|
| Table 4-1: List of electrostatic and other plasma interaction effects on space systems.....            | 22 |
| Table 7-1: Tested voltage-current combinations .....                                                   | 41 |
| Table 7-2: Typical inductance values for cables .....                                                  | 45 |
| Table C-1 : Parameters in different regions in space .....                                             | 71 |
| Table C-2 : Typical plasma parameters for LEO and GEO .....                                            | 82 |
| Table C-3 : Plasma conditions on exit plane of several electric propulsion thrusters.....              | 86 |
| Table C-4 : Emission versus backflow current magnitudes for several electric propulsion thrusters..... | 86 |
| Table C-5 : Value of $E_a$ for several materials .....                                                 | 90 |

## European Foreword

---

This document (prEN 16603-20-06:2019) has been prepared by Technical Committee CEN/CLC/TC 5 “Space”, the secretariat of which is held by DIN (Germany).

This document is currently submitted to the CEN ENQUIRY.

This document will supersede EN 16603-20-06:2014.

This document has been developed to cover specifically space systems and will therefore have precedence over any EN covering the same scope but with a wider domain of applicability (e.g.: aerospace).

## Introduction

---

The subject of spacecraft plasma interactions has been part of the spacecraft design process since spacecraft surface charging was first encountered as a problem in the earliest geostationary spacecraft. However, spacecraft surface charging is only one of the ways in which the space environment can adversely affect the electrical state of spacecraft and satellite technology has evolved over the years.

A need was identified for a standard that is up to date and comprehensive in its treatment of all the main environment-induced plasma and charging processes that can affect the performance of satellites in geostationary and medium and low Earth orbits. This standard is intended to be used by a number of users, with their own design rules, and therefore it has been done to be compatible with different alternative approaches.

This document aims to satisfy these needs and provides a consistent standard that can be used in design specifications. The requirements are based on the best current understanding of the processes involved and are not radical, building on existing de-facto standards in many cases.

As well as providing requirements, it aims to provide a straightforward brief explanation of the main effects so that interested parties at all stages of the design chain can have a common understanding of the problems faced and the meaning of the terms used. Guide for tailoring of the provisions for specific mission types are described in Annex B. Further description of the main processes are given in Annex C. Some techniques of simulation, testing and measurement are described in Annex D and Annex E.

Electrical interactions between the space environment and a spacecraft can arise from a number of external sources including the ambient plasma, radiation, electrical and magnetic fields and sunlight. The nature of these interactions and the environment itself can be modified by emissions from the spacecraft itself, e.g. electric propulsion, plasma contactors, secondary emission and photoemission. The consequences, in terms of hazards to spacecraft systems depend strongly on the sensitivity of electronic systems and the potential for coupling between sources of electrical transients and fields and electronic components.

Proper assessment of the effects of these processes is part of the system engineering process as defined in ECSS-E-ST-20. General assessments are performed in the early phases of a mission when consideration is given to e.g. orbit selection, mass budget, thermal protection, and materials and component selection policy. Further into the design of a spacecraft, careful consideration is given to material selection, coatings, radiation shielding and electronics protection.

This standard begins with an overview of the electrical effects occurring in space (Clause 4). The requirements, in terms of spacecraft testing, analysis and design that arise from these processes (Clause 5 to Clause 11) form the core of this document. Annex B holds a discussion of types of orbits and how to tailor the requirements according to the mission. Annex C discusses the quantitative assessment of the physical processes behind these main effects. Annex D describes computer simulations and Annex E describes testing and measurement.

# 1

## Scope

---

This standard is a standard within the ECSS hierarchy. It forms part of the electrical and electronic engineering discipline (ECSS-E-ST-20) of the engineering branch of the ECSS system (ECSS-E). It provides clear and consistent provisions to the application of measures to assess, in order to avoid and minimize hazardous effects arising from spacecraft charging and other environmental effects on a spacecraft's electrical behaviour.

This standard is applicable to any type of spacecraft including launchers, when above the atmosphere.

Although spacecraft systems are clearly subject to electrical interactions while still on Earth (e.g. lightning and static electricity from handling), these aspects are not covered, since they are common to terrestrial systems and covered elsewhere. Instead this standard covers electrical effects occurring in space (i.e. from the ionosphere upwards).

This standard may be tailored for the specific characteristic and constraints of a space project in conformance with ECSS-S-ST-00.

## 2

# Normative references

---

The following normative documents contain provisions which, through reference in this text, constitute provisions of this ECSS Standard. For dated references, subsequent amendments to, or revision of any of these publications do not apply, However, parties to agreements based on this ECSS Standard are encouraged to investigate the possibility of applying the more recent editions of the normative documents indicated below. For undated references, the latest edition of the publication referred to applies.

| EN reference   | Reference in text | Title                           |
|----------------|-------------------|---------------------------------|
| EN 16601-00-01 | ECSS-S-ST-00-01   | ECSS system - Glossary of terms |

## Terms, definitions and abbreviated terms

---

### 3.1 Terms defined in other standards

For the purpose of this Standard, the terms and definitions from ECSS-S-ST-00-01 apply.

### 3.2 Terms specific to the present standard

#### 3.2.1 aluminium equivalent thickness

thickness of aluminium with a mass density per unit area equal to that of the material being described

NOTE The mass density is normally measured in ( $\text{g cm}^{-2}$ ).

#### 3.2.2 auroral zone

region at a latitude between 60 and 70 degrees north or south where aurorae are formed

#### 3.2.3 deep-dielectric charging

electrical charge deposition within the bulk of an external or internal material

#### 3.2.4 dielectric

pertaining to a medium in which an electric field can be maintained

NOTE Depending on their resistivity, dielectric materials can be described as insulating, antistatic, moderately conductive or conductive. The following gives a classic example of classification according to the resistivity:

- more than  $10^9 \Omega \text{ m}$ : insulating
- between  $10^2 \Omega \text{ m}$  and  $10^9 \Omega \text{ m}$ : antistatic
- between  $10^3 \Omega \text{ m}$  and  $10^6 \Omega \text{ m}$ : static dissipative
- between  $10^{-2} \Omega \text{ m}$  and  $10^2 \Omega \text{ m}$ : moderately conductive
- less than  $10^{-2} \Omega \text{ m}$ : conductive

**3.2.5 dose**

energy absorbed locally per unit mass as a result of **radiation** exposure

**3.2.6 downstream**

<relating to an object at relative motion with respect to a **plasma**>  
on side of an object in the same direction as the **plasma** velocity vector

**3.2.7 electrostatic**

pertaining to static electricity or electricity at rest

**3.2.8 electrostatic breakdown**

failure of the insulation properties of a **dielectric**, resulting in a sudden release of charge and risk of damage to the **dielectric** concerned

**3.2.9 electrostatic discharge**

rapid, spontaneous transfer of electrical charge induced by a high **electrostatic** field

**3.2.10 external charging**

electric charge deposition on external materials

**3.2.11 flashover current**

current arising from a surface propagating discharge

**3.2.12 fluence**

time-integration of the flux

**3.2.13 insulator**

insulating **dielectric**

**3.2.14 internal charging**

electrical charge deposition on internal materials shielded at least by the spacecraft skin due to penetration of charged particles from the ambient medium

NOTE Materials can be conductors or dielectrics.

**3.2.15 internal dielectric charging**

internal charging of **dielectric** materials

**3.2.16 ion engine**

propulsion system which operates by expelling ions at high velocities

**3.2.17 L shell**

parameter of the geomagnetic field

NOTE 1 It is also referred as L, and is used as a co-ordinate to describe positions in near-Earth space.

NOTE 2 L or L shell has a complicated derivation based on an invariant of the motion of charged particles in the terrestrial magnetic field. However, it is useful in defining plasma regimes within the magnetosphere because, for a dipole magnetic field, it is equal to the geocentric altitude in Earth-radii of the local magnetic field line where it crosses the equator.

### 3.2.18 omnidirectional flux

scalar integral of the flux over all directions

NOTE This implies that no consideration is taken of the directional distribution of the particles which can be non-isotropic. The flux at a point is the number of particles crossing a sphere of unit cross-sectional surface area (i.e. of radius). An omnidirectional flux is not to be confused with an isotropic flux.

### 3.2.19 outgassing rate

mass of molecular species evolving from a material per unit time and unit surface area

NOTE The units of outgassing rates are  $\text{g cm}^{-2} \text{s}^{-1}$ . It can also be given in other units, such as in relative mass unit per time unit: ( $\text{g s}^{-1}$ ), ( $\% \text{s}^{-1}$ ) or ( $\% \text{s}^{-1} \text{cm}^{-2}$ ).

### 3.2.20 plasma

partly or wholly ionized gas whose particles exhibit collective behaviour through its electromagnetic field

### 3.2.21 primary discharge

initial electrostatic discharge which, by creating a temporary conductive path, can lead to a secondary arc

### 3.2.22 radiation

transfer of energy by means of a particle (including photons)

NOTE In the context of this Standard, electromagnetic radiation below the UV band is excluded. This therefore excludes visible, thermal, microwave and radio-wave radiation.

### 3.2.23 radiation belt

area of trapped or quasi-trapped energetic particles, contained by the Earth's magnetic field

### 3.2.24 ram

volume adjacent to the spacecraft and located in the same direction of the spacecraft motion where modification to the surface or **plasma** can occur due to the passage of the spacecraft through the medium

#### 3.2.25 secondary arc

passage of current from an external source, such as a solar array, through a conductive path initially generated by a **primary discharge**

#### 3.2.26 surface charging

electrical charge deposition on the surface of an external or internal material

#### 3.2.27 tether

flexible conductive or non-conductive cable linking two spacecraft or two parts of the same spacecraft not mechanically attached in any other way

#### 3.2.28 thruster

device for altering the attitude or orbit of a spacecraft in space through reaction

NOTE E.g. rocket, cold-gas emitter, and electric propulsion.

#### 3.2.29 triple point

<relating to onset of electrostatic discharge>  
point where **dielectric**, metal and vacuum meet

#### 3.2.30 upstream

<relating to an object at relative motion with respect to a **plasma**>  
on the side of the object in the opposite direction to the **plasma** velocity vector

#### 3.2.31 wake

volume adjacent to a spacecraft and located in the opposite direction to the spacecraft motion where the ambient **plasma** is modified by the passage of the spacecraft through the medium

### 3.3 Abbreviated terms

The following abbreviated terms are defined and used within this Standard.

| Abbreviation | Meaning                                |
|--------------|----------------------------------------|
| AOCS         | attitude and orbital control system    |
| DGD          | direct gradient discharge              |
| EMC          | electromagnetic compatibility          |
| emf          | electro-motive force                   |
| EP           | electric propulsion                    |
| ESD          | electrostatic discharge                |
| ETFE         | ethylene-tetrafluoroethylene copolymer |
| eV           | electron volt (also keV, MeV)          |
| FEPP         | field emission electric propulsion     |
| FEP          | fluoroethylene-propylene               |

|        |                                               |
|--------|-----------------------------------------------|
| GEO    | geostationary Earth orbit                     |
| HEO    | highly eccentric orbit                        |
| ISS    | International Space Station                   |
| IVG    | inverted voltage gradient                     |
| IVGD   | inverted voltage gradient discharge           |
| LEO    | low Earth orbit                               |
| MEMS   | micro-electromechanical system(s)             |
| MEO    | medium (altitude) Earth orbit                 |
| MLI    | multi-layer insulation                        |
| MLT    | magnetic local time                           |
| NASA   | National Aeronautics and Space Administration |
| NGD    | normal gradient discharge                     |
| PCB    | printed circuit board                         |
| PEO    | polar Earth orbit                             |
| PTFE   | poly-tetrafluoroethylene                      |
| PVA    | photo-voltaic assembly                        |
| RIC    | radiation induced conductivity                |
| r.m.s. | root-mean-square                              |
| SAS    | solar array simulator                         |
| SPIS   | spacecraft plasma interaction simulation      |
| SPT    | stationary plasma thruster                    |
| SSM    | second surface mirror                         |
| UV     | ultra-violet light                            |

### 3.4 Nomenclature

The following nomenclature applies throughout this document:

- a. The word “shall” is used in this Standard to express requirements. All the requirements are expressed with the word “shall”.
- b. The word “should” is used in this Standard to express recommendations. All the recommendations are expressed with the word “should”.

NOTE It is expected that, during tailoring, recommendations in this document are either converted into requirements or tailored out.

- c. The words “may” and “need not” are used in this Standard to express positive and negative permissions, respectively. All the positive permissions are expressed with the word “may”. All the negative permissions are expressed with the words “need not”.
- d. The word “can” is used in this Standard to express capabilities or possibilities, and therefore, if not accompanied by one of the previous words, it implies descriptive text.

NOTE In ECSS “may” and “can” have completely different meanings: “may” is normative (permission), and “can” is descriptive.

- e. The present and past tenses are used in this Standard to express statements of fact, and therefore they imply descriptive text.

# 4

## Overview

---

### 4.1 Plasma interaction effects

#### 4.1.1 Presentation

Most spacecraft engineers have come across the term space plasma because of the potential risk it represents in leading to high-level spacecraft charging and related electrostatic discharges. Such a phenomenon is a critical environment hazards for satellites, especially in high altitude orbits (including in geostationary orbit). However, there are numerous other plasma interaction effects of which it is also important to be aware, in order to improve engineering design and to optimize the behaviour of space systems in the space plasma environment. Not all spacecraft-plasma interactions are adverse. For example, electrodynamic tethers use current collection from the plasma to complete their electrical circuit and generate power or thrust. Scientific instruments can exploit spacecraft plasma interactions to make plasma measurements, and a magnetospheric propulsion system has been proposed to use plasma interactions with an artificial magnetic field as a propulsion system.

This clause briefly introduces the various effects covered by this standard. The most common engineering issues are first briefly described in clause 4.1.2 while a short overview of the physical mechanisms involved is given in the second of this section.

#### 4.1.2 Most common engineering concerns

The following are the most common engineering concerns related to electrical charging of a spacecraft:

- **Surface charging** due to charge accumulation on spacecraft surface is a potential cause of spacecraft anomalies. High levels of differential potential can lead to ESDs which can couple to spacecraft electronics and damage electronic components. Initial ESDs can also trigger the generation of secondary arcs on high voltage systems. Several occurrences of permanent solar array power loss in space are believed to be related to such phenomena.
- **Internal charging** due to penetrating electrons is another cause of spacecraft anomalies. ESDs can be generated within the spacecraft Faraday cage and in close proximity to vulnerable components.

- **Current leakage** affects exposed high voltage systems which can experience significant power loss due to current leakage sustained by freely moving particles (from the plasma or photo-electrons).
- **Environment modification** occurs as a bi-product of surface charging and/or particle emission by surfaces. Electric charge and plasma density are affected in a volume that can extend very far from the spacecraft (many times its typical dimension). This is usually a critical problem for scientific plasma measurements that cannot retrieve the natural parameters to be measured without taking these alterations into account.
- **Electric propulsion** actively modifies the local environment and creates a local plasma population and modifies the current balance of the satellite that otherwise can occur. It can affect other spacecraft systems, e.g. by increased contamination.
- **Electrostatic tethers** make use of current collection from the ambient medium to allow a current to pass. These also change the currents passing through the system and can lead to high potentials.

Table 4-1 contains a more complete list of the various effects in which space plasma plays an important role.

A quantitative description of the most important processes in spacecraft-plasma interactions is given in Annex C but a brief qualitative overview follows here.

### 4.1.3 Overview of physical mechanisms

Surface charging occurs because electric charges (electrons and ions) of the plasma are free to move and eventually get trapped on material surfaces when they hit them. Electrons and ions provide negative and positive current respectively. Both electrons and ions can also expel electrons when they hit the surface, providing an additional positive current. UV and soft X-ray photons coming from the Sun also have enough energy to expel electrons from materials, thereby providing a positive current. The accumulation of charge (positive or negative) leads to the creation of a potential that eventually prevents further charge accumulation by repelling charges of a given polarity and attracting charges of opposite polarity. Different surfaces on the same spacecraft can charge to very different potentials, resulting in strong local electric fields. Photo-emission and secondary yield are important factors in determining occurrence of high level differential charging. Charging effect is highly dynamic as the plasma populations can change rapidly.

Internal charging occurs because higher energy electrons are able to penetrate thin surfaces and deposit charge in or on materials within the spacecraft. Internal charging involves lower currents but potentials can build up over longer periods on materials with low resistivity because current through the structure is the only mechanism by which charge can be removed. Strong electric fields again are the result.

An important hazard related to charging (surface and internal) is sudden electrostatic discharge (ESD). ESDs are most likely initiated by field effect emission and avalanche process at so-called 'triple-points', where metal, dielectric and vacuum are found together. This can eventually result in the injection of high current electrical transients into the spacecraft electrical

system. This can cause transient state changes in electronics or permanent damage of material coating or electronic components. In the vicinity of high potential differences, plasma released in an ESD can trigger a secondary discharge or even a sustained arc if the potential is maintained e.g. by the solar array.

**Table 4-1: List of electrostatic and other plasma interaction effects on space systems**

|                                                                                                                                                                                                                                                                                                         |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Spacecraft reference potential change (e.g. so-called spacecraft high voltage charging)                                                                                                                                                                                                                 |
| Differential surface charging                                                                                                                                                                                                                                                                           |
| Internal surface charging                                                                                                                                                                                                                                                                               |
| Deep-dielectric charging                                                                                                                                                                                                                                                                                |
| Surface charging effects on e.g. plasma instruments                                                                                                                                                                                                                                                     |
| Charging interactions with thruster plumes                                                                                                                                                                                                                                                              |
| Charging induced sputtering                                                                                                                                                                                                                                                                             |
| Charging induced contamination                                                                                                                                                                                                                                                                          |
| Dust charging and sticking                                                                                                                                                                                                                                                                              |
| Electrostatic sticking (SA, inflatables, solar sails, dusts)                                                                                                                                                                                                                                            |
| Charging differences in docking procedures and EVA                                                                                                                                                                                                                                                      |
| Material modifications (e.g. electric field induced conductivity, plasma-contaminant modifications, cracking e.g. of ITO)                                                                                                                                                                               |
| Tether systems and $\mathbf{v} \times \mathbf{B}$ induced voltages and currents                                                                                                                                                                                                                         |
| Interference induced by electrostatic sheath and induced plasma on EM systems                                                                                                                                                                                                                           |
| Spontaneous discharges                                                                                                                                                                                                                                                                                  |
| Triggered discharges: <ul style="list-style-type: none"> <li>- Thruster-triggered</li> <li>- Low voltage discharges (e.g. Paschen and secondaries)</li> <li>- Sunlit/shadow triggered discharges</li> <li>- triggered by micro particles</li> <li>- triggered by natural high density plasma</li> </ul> |
| Synergistic secondary low-voltage discharges (e.g. on solar array)                                                                                                                                                                                                                                      |
| Power loss and current flow from exposed elevated voltage systems                                                                                                                                                                                                                                       |
| Photoelectron cloud induced charging and disturbance of plasma sensors                                                                                                                                                                                                                                  |
| Plasma perturbation from microparticle impacts (e.g. antennas)                                                                                                                                                                                                                                          |
| Active plasma sources (e.g. emitters, thrusters, contactors)                                                                                                                                                                                                                                            |

If a surface is maintained at high potential, it draws a current from the plasma, particularly in the dense LEO environment. This is an issue with exposed solar array interconnects because this leakage current drains power from the array. In addition the floating potential of the spacecraft can be altered as a result.

The magnitude of spacecraft plasma interaction effects varies greatly with the changes in the ambient plasma from one type of Earth orbit to another. Also the plasma environment can exhibit temporal changes along the orbit and as a result of so-called ‘Space Weather’. In addition, the spacecraft itself can modify the plasma environment e.g. via thruster firings, active experiments, or debris impacts. Other aspects of the space environment besides plasma can also influence the plasma interaction e.g. radiation, contamination, and temperature.

In any case, it is important to have access to a good quantitative description of the space environment. Suitable descriptions and models of the space environment, including aspects that control charging effects, can be found in ECSS-E-ST-10-04.

## 4.2 Relationship with other standards

This standard is a standard within the engineering branch. It relies on the following ECSS standards:

ECSS-E-ST-10 “Space engineering – System engineering general requirements”

ECSS-E-ST-20 “Space engineering - Electrical and electronic”

A number of ECSS standards are related to this Standard:

- The environment, defined by ECSS-E-ST-10-04 “Space engineering - Space environment”, is an input to the analysis of charging and related effects described in this document.
- Radiation transport as described in ECSS-E-ST-10-12 “Space engineering - Method for the calculation of radiation received and its effects, and a policy for design margins” has relevance to internal charging effects described in this document.
- Secondary electron emission is a feature of surface charging effects described in this document and in multipaction as described in ECSS-E-ST-20-01 “Space engineering – Multipaction design and test”.
- Testing of electrostatic behaviour shares many techniques with general electromagnetic cleanliness. Hence ECSS-E-ST-20-07 “Space engineering – Electromagnetic compatibility” interfaces with this standard.
- Charging of solar arrays is an important charging hazard. Hence ECSS-E-ST-20-08 “Space engineering – Photovoltaic assemblies and components” interfaces with this standard.
- This standard specifies the selection of materials and components according to their electrical behaviour, in order to avoid hazardous effects. Electrical properties are not the only consideration and ECSS-Q-ST-70-71 “Space product assurance - Data for selection of space materials and processes” describe complementary information.
- ECSS-E-ST-10-02 “Space engineering – Verification” specifies the concepts behind verification processes in general, the criteria for defining a verification strategy and rules for its implementation. It includes a description of the documentation associated to the verification process, and provisions on specific aspects of the verification process.

- ECSS-E-ST-10-03 “Space engineering – Testing” gives standard environmental and performance test requirements for a space system and its constituents. It defines the general test requirements for products and systems that are generally applicable to all projects. It also defines the documentation associated with testing activities.

## 5

# Protection programme

---

- a. For any spacecraft, the supplier shall establish, at the start of the project, a plan for the assessment and mitigation of hazards associated with electrical interactions with the environment in conformance with Annex A.
- b. The compliance of the design with the design requirements shall be verified through measurement, inspection and testing.

## Surface material requirements

---

### 6.1 Overview

#### 6.1.1 Description and applicability

The phenomenon of surface charging leads to requirements to control the electrical behaviour of materials directly in contact with the ambient plasma. These materials can become the source of electrostatic discharges whose principal hazardous effect is to cause damage to electronic systems elsewhere on the spacecraft and of undesired electric fields, whose principal effect is to interfere with measurements of the ambient medium. The components affected include any spacecraft material on the outer surface of the spacecraft, e.g. thermal blankets, solar cell cover glass, sensor optics, exposed cables.

In addition, thin films, e.g. thermal blankets, sometimes do not shield underlying materials from the electrons mainly responsible for high level surface charging (~ 10 keV to 50 keV). Hence components affected include any spacecraft material covered by only a thin film, with thickness equivalent to less than 100 micro-meters Aluminium (0,03 g/cm<sup>2</sup>), including multi-layer insulation. The requirements in this clause also apply to surfaces partly exposed to space through small apertures (e.g., venting holes), although holes can be designed so as to avoid direct exposure.

Another factor influencing charging levels is the conduction path from each surface to ground and to other parts on the spacecraft. Hence these requirements cover all components concerned with the grounding and electrical continuity of the spacecraft structure, subsystems and electronics.

In addition to considering components that affect the build-up of charge, the effects of any resulting electrostatic discharges, i.e. coupling to sensitive devices, are controlled in order to prevent discharges causing damage and interference to systems elsewhere. This is an EMC issue that is common to electrical transients, however generated. Because this is part of general EMC design, specific requirements are not included here but standard EMC procedures are applied to control the transmission of transients.

These requirements also cover solar arrays and there are additional specific requirements for these due to the possibility of secondary discharges, fed by the power of the array itself, in clause 7.

### 6.1.2 Purpose common to all spacecraft

The main purpose of the requirements in this clause is to reduce differential charging and therefore the risk of electrostatic discharge or its power below an acceptable level. This is achieved principally by effective grounding throughout the spacecraft.

### 6.1.3 A special case: scientific spacecraft with plasma measurement instruments

Scientific spacecraft, which have the measurement of ambient electric field or of low energy particles as part of their mission, have more stringent requirements in terms of differential charging, absolute spacecraft potentials and contamination by spacecraft generated particles. For this reason, clause 6.7 provides specific requirements for this case.

Since quantitative requirements are often mission specific, the requirements in clause 6.7 are not intended to be exhaustive, but to cover the common aspects that can be expected in most of the scientific missions.

For each science mission the scientific community assesses the need for a neutralizer (ion or electron emitter) is used to mitigate the positive or negative floating potential of the spacecraft. This device can be supplied as part of the scientific payload or included in the supplier contract.

Plasma contactors are generally avoided on scientific spacecraft because of the large scale disturbance they induce on scientific measurements.

In practice the reduction of photo-electron and secondary electron emission is often achievable by active potential control techniques only.

## 6.2 General requirements

### 6.2.1 Maximum permitted voltage

- a. In order to avoid electrostatic discharge, the following critical voltages and electric fields shall be used:
1. To avoid electrostatic discharges, a maximum electric field within the dielectric of  $10^7$  V/m.
  2. To avoid electrostatic discharges in normal potential gradient a maximum differential voltage between a dielectric and an adjacent conductor of -2000 V.
  3. To avoid an electrostatic discharge in inverted voltage gradient, a maximum differential voltage between a dielectric and an adjacent conductor exposed to the vacuum of +300 V.

NOTE 1 Maximum permitted voltages specified for scientific missions including field or plasma measurement can be lower than the limits above to limit contamination of environmental measurements.

NOTE 2 An inverted voltage gradient is between a dielectric and a conductor at a more negative potential.

NOTE 3 A normal voltage gradient is between a dielectric and a conductor at a more positive potential.

NOTE 4 These voltage limits do not include margin for the possible inaccuracy of analysis by simulation.

NOTE 5 Electric fields can be locally enhanced by sharp edges.

- b. If the limits specified in 6.2.1a are not met, the assembly shall be submitted to charging tests as described in clause 6.6.
- c. The test specified in requirement 6.2.1b may be replaced by an ESD analysis under the condition that the ESD responsible agrees that the result of this analysis demonstrate that the effect of such a worst-case ESD is acceptable.

## 6.2.2 Maximum resistivity

- a. In order to limit differential voltage, a maximum current density of  $J = 10 \text{ nA/cm}^2$  through the dielectric shall be used to calculate the maximum resistivity of dielectric materials.

NOTE This current is a recommended upper bound of the current through dielectric material to other parts on Earth orbiting spacecraft. It is not the electron irradiation current used for testing.. For example, a small sunlit area of aluminium coupled to a larger area of material in eclipse can lead to a current flow through a dielectric beneath the aluminium as large as the photocurrents ( $\sim 4 \text{ nA/cm}^2$  for aluminium) plus any difference in secondary emission current.

- b. The method used for resistivity measurement shall be justified.

NOTE Some methods are described in Annex D.3.

## 6.3 Electrical continuity, including surfaces and structural and mechanical parts

### 6.3.1 Grounding of surface metallic parts

- a. To prevent ESD events, all structural and mechanical parts shall be electrically bonded to each other, ensuring that, in order to control differential charging, there is a resistance of less than  $10^6 \Omega$  at each bond.

NOTE 1 For example, for electrical boxes.

NOTE 2 EMC requirements can be more restrictive than this.  
For EMC requirements, see ECSS-E-ST-20-07.

- b. <<deleted>>
- c. Where structural ground is carried across slip-rings on a rotating joint, at least two slip-rings shall be dedicated to the structural ground path, some at each end of the slip-ring set.

NOTE This is to provide redundancy.

- d. <<deleted>>
- e. <<deleted>>
- f. Circuits and conductive elements shall remain grounded in all possible situations

NOTE E.g. contacts and cables in switched circuits and moveable conductors.

- g. The grounding of surface conductors shall be implemented in one of the following two ways:
1. Make the grounding to the main spacecraft of external and internal metallic parts and intrinsically conductive parts, like carbon, by a resistance of a value that satisfies requirement in clause 4.2.11 of ECSS-E-ST-20-07.
  2. Select the resistance to spacecraft ground not to be exceeded, such that it ensures that metal parts do not float by over  $V_{MAX}$  absolute potential with respect to spacecraft ground as specified in requirement 6.2.1a.

NOTE This normally leads to a requirement that the product of the resistance  $R$  and the area exposed to the environment  $A$ , is such that

$$R \cdot A \leq \frac{V_{MAX}}{J}$$

For a  $V_{MAX}$  of 300 V and  $J = 10 \text{ nA cm}^{-2}$ ,

$$RA \leq 3 \times 10^6 \text{ } \Omega \text{ m}^2$$

For example:

- For a one square metre MLI, the maximum resistance is  $3 \text{ M}\Omega$
- For a scientific mission where  $V_{MAX}=10 \text{ V}$ ,  
 $RA \leq 10^5 \text{ } \Omega \text{ m}^2$

### 6.3.2 Exceptions

- a. Except in the case specified in 6.3.2c, floating conductive parts may be used if they have an area less than  $1 \text{ cm}^2$  and have a total capacitance less than  $50 \text{ pF}$  with respect to the structure and not be part of a multi-conductor elements structure and are more than  $20 \text{ mm}$  away from a power line.

NOTE 1 This is to limit the energy available to discharge.

NOTE 2 Multi-conductor structures exist where at least two conductive elements are separated by a dielectric surface of less than 100 cm<sup>2</sup>.

- b. The configuration shall be such that energy involved in any possible discharge is less than one corresponding to a discharge of a capacitance of 50 pF under  $6 \times 10^3$  V.
- c. In case of multiple elements, in which case the empirical rule in 6.3.2a does not apply, tests shall be performed.

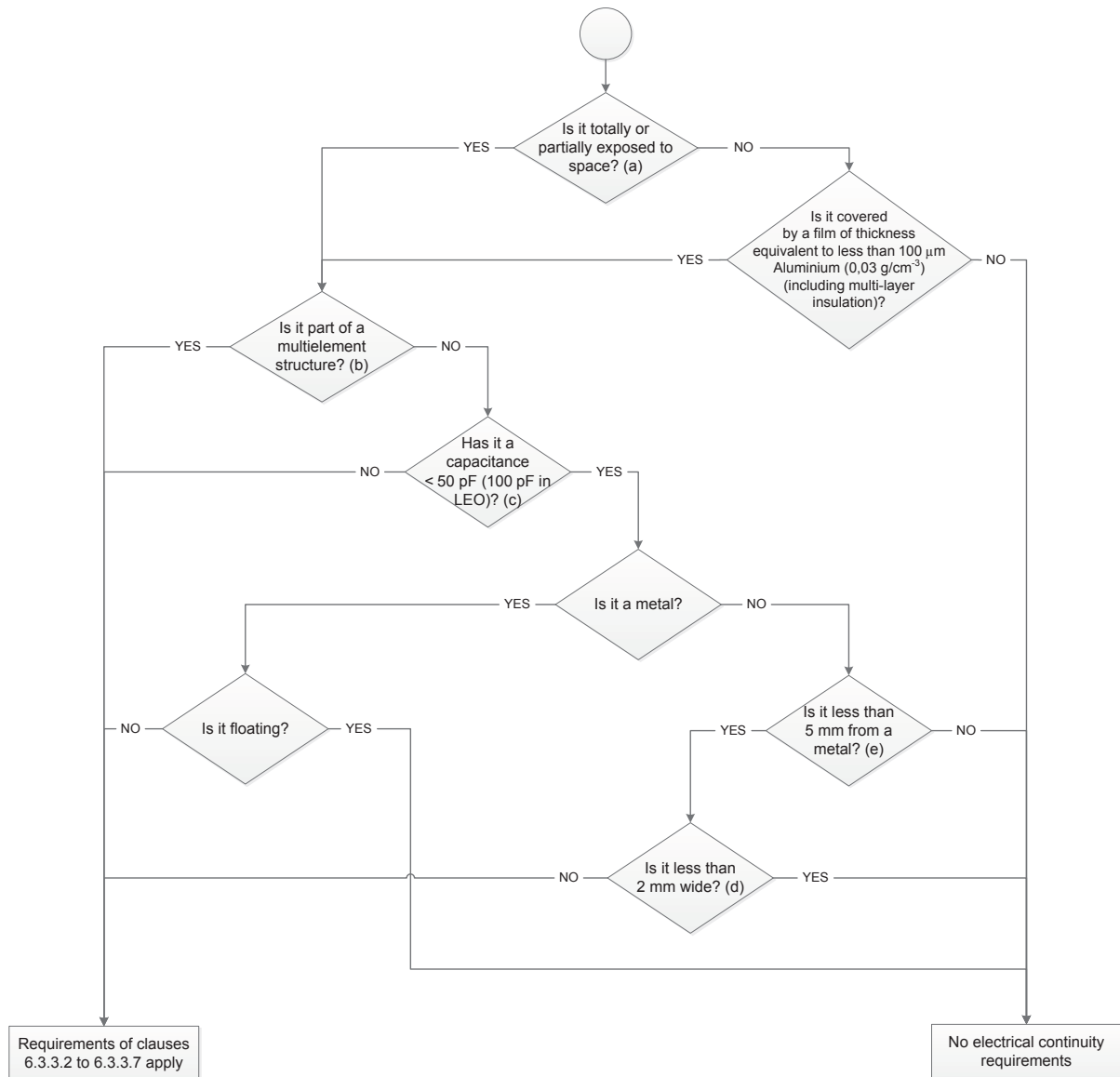
NOTE 1 Examples are patched antenna and solar arrays are multiple elements.

NOTE 2 See 6.3.1d NOTE for definition of a multi-conductor structures.

### **6.3.3 Electrical continuity for surface materials**

#### **6.3.3.1 Applicability**

- a. The applicability of the electrical continuity requirements shall be established in accordance with the diagram in Figure 6-1.



(a) Surfaces partially exposed include those exposed through small apertures such as venting holes.

(b) Multi-conductor structures exist where at least two conductive elements are separated by a dielectric surface of less than 100 cm<sup>2</sup>.

(c) A capacitance of less than 50 pF is typically the case where the surface area is less than 1 cm<sup>2</sup>. Keeping the capacitance low limits the size of any discharge. In LEO the short charging time as the spacecraft crosses the aurora limits the size of discharge even with a capacitor up to 100 pF.

(d) Two dielectric patches within a 100 cm<sup>2</sup> area are considered as one single dielectric for area or width estimates.

(e) This forms a triple point. For the definition of "triple point" see clause 3.2. An example where this is important is the spot of non-conductive glue used to stick wires near the ends of an array string from the bare ends.

Figure 6-1: Applicability of electrical continuity requirements

### 6.3.3.2 General

- All spacecraft surface materials shall be conductive to the extent that they lead to surface voltage below the maximum voltage specified in clause 6.2.1.
- If a surface material is used which is not conductive, to the extent specified in 6.3.3.2a, then it shall be verified by testing or appropriate charging analysis in accordance with clause 6.4, whether hazardous charging can occur under representative worst case conditions.

- c. The determination of dc resistance of the surface material shall include the change over the service life of the bond in the environmental conditions which it is expected to experience including vacuum, temperature and mechanical stress.

#### **6.3.3.3 Blankets**

- a. All external and internal metallic layers of a thermal blanket shall be grounded to the structure with at least 2 bonding straps directly to ground (no daisy chain configuration).
- b. Any point on a blanket shall be within 1 m of a bonding strap.
- c. Adjacent blankets greater than 100 cm<sup>2</sup> in area shall be separately grounded to structure.

#### **6.3.3.4 Material assemblies**

- a. Material assemblies composed of different materials that are not separately grounded, shall be analysed or tested in their entirety.

NOTE 1 An example is optical solar reflectors.

NOTE 2 A complicated assembly, e.g. with high number of different layers, or not well represented by dielectrics coating planar surfaces, can be difficult to simulate in the analysis tools and then testing is needed in accordance with this requirement.

- b. Metallic layers within material assemblies shall not be exposed to the plasma.

#### **6.3.3.5 Conductive coatings**

- a. The thickness of conductive coatings shall be such that there is no degradation of their performance as a conductor when exposed to the expected erosion due to sputtering and atomic oxygen.

#### **6.3.3.6 Dielectric materials**

- a. The following materials shall not be used unless it can be demonstrated by charging analysis with proper 3D computation tool that they pose no threat to the spacecraft:

1. Perforated metallized FEP or ETFE (SSM)
2. Polyimide material with thickness above 50 µm if no ESD conductive coating is used on the space-exposed side
3. FEP, ETFE, C<sub>2</sub>F<sub>4</sub>
4. Epoxy glass
5. Silica cloth

NOTE The reason is that they have a known association with ESD risks.